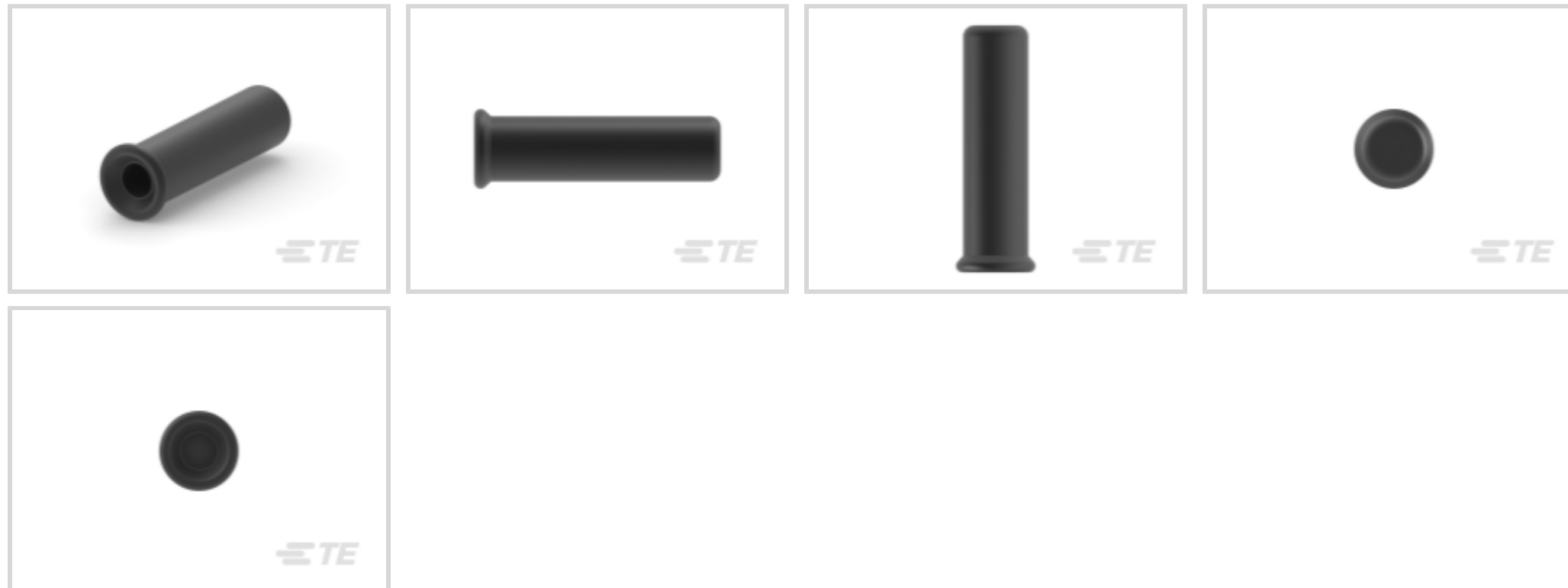




Connectors > Socket Connectors > Pin Sockets > Miniature Spring Sockets: Closed Bottom, Beryllium Copper, 6.5A



Socket Length: 6.6 mm [.26 in]

PCB Hole Diameter: 1.83 mm [.072 in]

Socket Sleeve Style: **Closed Bottom**

Wire Size: .518 – .823 mm²

[All Miniature Spring Sockets: Closed Bottom, Beryllium Copper, 6.5A \(10\)](#)

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Socket Sleeve Style	Closed Bottom
Connector System	Cable-to-Board
Sealable	No

Configuration Features

Compatible With Wire & Cable Type	Discrete Wire
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Body Features

Sleeve Material	Copper
Sleeve Plating Material	Tin

Contact Features

Contact Spring Plating Material	Gold
Contact Spring Plating Thickness	.127 μm[30 μin]
Contact Mating Area Plating Material Thickness	30 μm[30 μin]
Contact Base Material	Beryllium Copper

Contact Current Rating (Max)	6.5 A
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Termination Features

Insertion Method	Hand/Semi-Automatic
Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Termination Method to Wire & Cable	Solder

Dimensions

PCB Thickness (Recommended)	.79 – 3.18 mm [.031 – .125 in]
Socket Length	6.6 mm [.26 in]
PCB Hole Diameter	1.83 mm [.072 in]
Wire Size	.518 – .823 mm ²
Mating Pin Diameter Range	.86 – 1.04 mm [.034 – .041 in]

Usage Conditions

Operating Temperature Range	-65 – 125 °C [-85 – 257 °F]
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Operation/Application

Solder Process Feature	None
Circuit Application	Power & Signal

Packaging Features

Packaging Quantity	2000
Packaging Method	Bag, Loose Piece

Other

Spring Material	Beryllium Copper
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC

Free

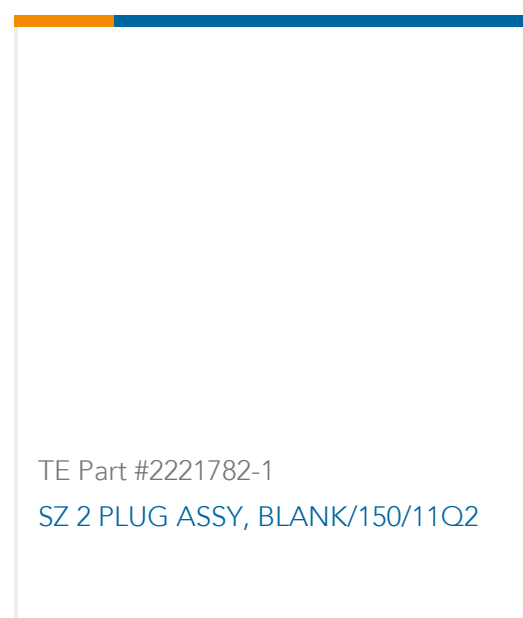
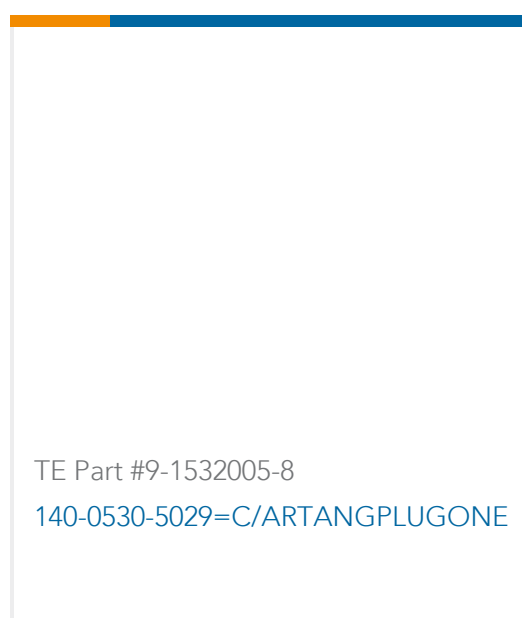
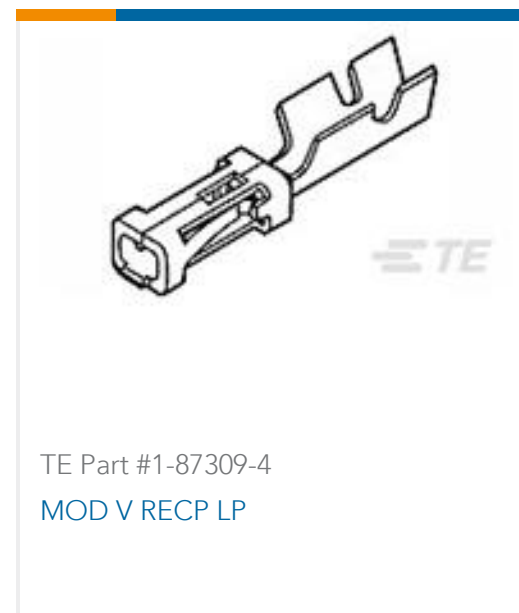
Solder Process Capability

Pin-in-Paste capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Customers Also Bought



Documents

CAD Files

Customer View Model

[ENG_CVM_CVM_50865-5_V.2d_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_50865-5_V.3d_igs.zip](#)

English

Customer View Model



[ENG_CVM_CVM_50865-5_V.3d_stp.zip](#)

English

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